

Curriculum Vitae
Jan van Kempen.

Personalialia:

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Employment and responsibilities.

Since 1-7-1977 employed at Philips Semiconductors (from 2006 onwards known as NXP).

- 2005-2010: Package Innovation Nijmegen.
 - Cost reduction manager
 - Responsibilities:
 - Initiate and coordination of cost reduction activities in the assembly sides.
 - Package innovation engineering.
 - Achievements:
 - Miniaturization breakthrough in leadless packages.
 - Participation in multiple successful 8D teams (complex customer complaints).
 - Development of optical joystick.
 - Within this assignment business trips were made to:
 - N. America, Thailand, Taiwan, Philippines, Hong Kong, Austria, Slovakia, Spain
- 2002-2004: Business Line Standard Logic Nijmegen.
 - Assembly Technology Innovation & Coordination manager.
 - Responsibilities:
 - Package roadmap development for standard IC's.
 - Coordination of package developments.
 - Driver of assembly cost reduction activities.
 - Interface between marketing and assembly.
 - Interface Product development, Quality / reliability departments and assembly.
 - Resource for Regional Sales Offices for assembly related questions.
 - Support assembly related customer complaint handling /corr. actions.
 - Driver / supporting ecological package roadmap (e.g. Pb-free).
 - Achievements:
 - Introduction of 2 low pin-count leadless package platforms (DQFN, XSON).
 - More than ten different thin packages released in this timeframe.
 - Cost reduction targets TSSOP packages where achieved /exceeded.
 - Ecological targets achieved before European RoHS deadline 01-06-06.
 - Within this assignment business trips were made to:
 - N. America, Thailand
- 1994-2001: Package Innovation Nijmegen.
 - Package Innovation engineering
 - Responsibilities:
 - Initiate and coordination of cost reduction activities in the Philips assembly sides.
 - Project management of package development (e.g. SMD and Power packages).
 - Co-development of the advanced integrated line (AIMS line in Bangkok).
 - Achievements:
 - Cost reduction on packing material of more the 70% between 1996 and 2000.
 - Introduction Eco-reel, re-use policy, scrap reduction, tray consignment.
 - Copper wire introduction in Power packages.
 - Delivery of AIM's line was in-time, within spec. and within budget.
 - Within this assignment business trips were made to:
 - Thailand, Taiwan, N. America, Japan, Philippines Spain, Switzerland, Austria, Germany, Hong Kong, Mainland China.

- 1983-1993: Service and participation in the development of assembly equipment.
 - Installation, training and trouble shooting of assembly equipment (die-, wire-bonders, molding).
 - Multiple visits to Taiwan, Philippines, Thailand, Hong Kong, Brazil, N. America, Germany, France.
 - 1992-1993 Residence: Bangkok (Thailand).
 - Responsible for assembly equipment upgrade activities.
 - Replacement of CPU and vision systems in installed base of wire- and die-bonder.
 - Expanding capability of installed Philips die-bonders from 4" to 6"
 - Interim director of development department.
 - 1991: Residence: Kaohsiung (Taiwan).
 - Know-how transfer for development of assembly equipment to Kaohsiung (Taiwan).
 - Replacement of CPU and vision systems in installed base of wire- and die-bonder.
 - Expanding capability of installed Philips die-bonders from 4" to 6"
 - 1985-1987 Residence: Kokomo Indiana (USA).
 - Assignment in the USA at Delco electronics (part of GM who bought Philips assembly equipment).
 - Responsible for training, yield and line improvements of the equipment.
 - Achievements: met / exceeded the pre-set target.
- 1977-1982: Quality laboratory Standard Logic products (Nijmegen).
 - Responsible for failure analyses team.
 - Introduction of new methods which did bring the score rate of successful analyses from <50 to > 90%.
 - Coordination and responsibility of know-how transfer for failure analyses to Taiwan. (temporary assignment in Kaohsiung to support this activity).

Additional information:

- Skilled in English (written and spoken).
- Skilled in German (spoken, less skilled for the written part).
- French skill is available but limited.
- Assignments / business trips abroad during the total Philips/NXP employment sums up to more than 10 years.
- Inventor and co-inventor of several patents.
- Driving licence.
- Active in sports (mainly in-door soccer and bike riding).
- Living on the "country side" and supervise a small nature park with owned Scottish Highlanders.
- Very active in house building and renovation.

Education:

Bachelor level with an additional teacher's degree.

Additional training courses:

- Statistics.
 - System architecture CPU's.
 - Quality training: 8D approach.
 - Project management training.
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